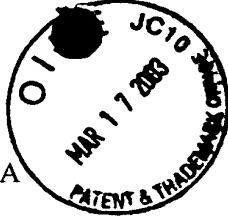


Docket No.: 4459-018A



#11  
Misc Letter  
PATENT  
Robinson  
5/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Chun Hung LIN

Serial No. 09/854,487

Group Art Unit: 2826

Filed: May 15, 2001

Examiner: A. Williams

For: LOW-PIN-COUNT CHIP PACKAGE HAVING CONCAVE DIE PAD AND/OR  
CONNECTIONS PADS (as amended)

**STATEMENT OF COMMON OWNERSHIP**

COMMISSIONER FOR PATENTS

Washington, D. C. 20231

Sir:

The undersigned, an Attorney of record, hereby states that:

The above-captioned application and U.S. Patent No. US 6,342,730B1 to Jung et al. were, at the time the invention of the above-captioned application was made, subject to an obligation of assignment to the same company, i.e., Advanced Semiconductor Engineering, Inc.

Respectfully submitted,

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